CALL FOR PAPERS

The Leading International Components, Packaging, and Manufacturing Technology Symposium

11th. IEEE CPMT Symposium Japan

November 9 – 11, 2022,
A Hybrid Event of On-site and Virtual Meetings

On-site Venue: Kyoto University Clock Tower Centennial Hall, Kyoto, JAPAN
https://www.ieee-csj.org/

“Electronics Packaging meets DX”
- Heterogeneous Integration for the next Wellbeing & Sustainability

“IEEE CPMT Symposium Japan (ICSJ)” is one of the most widely recognized international conferences sponsored by the IEEE Electronics Packaging Society (EPS) and has been held annually in Kyoto in November. This conference was inaugurated in 1992 as “The VLSI Packaging Workshop in Japan (VPWJ)” to provide a platform for you to communicate and interact with global leaders in packaging technology. Later in 2010, this conference was renamed to “ICSJ” and ICSJ2022 is the 11th. ICSJ meeting, or 20th. conference since establishing VPWJ. Even still vague situation with COVID19, following the last year, ICSJ2022 will be a hybrid event of on-site and virtual meetings where several presentation options are available for the authors to select and the details will be announced on the official website at a later date.

Electronics Packaging meets DX (Digital Transformation) - Heterogeneous Integration for the next Wellbeing & Sustainability: For several years with Pandemic, our whole life-style and communications, even economical supply chains are dramatically changed and rapid digital transformation is required. The 5G commercial services have begun and provide higher transmission rate, lower latency, greater capacity of remote execution, and larger number of connected devices. Driven by AI, 5G, smartphone, automotive and IoT, the demand for advanced manufacturing processes has increased as well. Innovation in electronics and packaging technologies are the underlying pillar, serving society, especially global public health across the entire planet. The symposium tries to forecast where the packaging technology is heading. In 2022, our focus is on key electronics packaging technologies for the next-generation mobile networks and their applications for sustainable well-being for people and society, and emphasizes on the following main topics: Photonics, Advanced Packaging, Process & Material, Power & Automotive Electronics, Bioelectronics & Healthcare, and Signal/Power Integrity. Additional topics of primary interest to the participants are listed below.

Other topics include (but not limited to):
+ 3D Packaging & Chip-on-Chip
+ Advanced Fine Pitch Packaging, Micro Bumping & CSP
+ Board-Level Integration & Integrated Substrate
+ Laminated Materials & Processing, Materials for Packaging
+ Reliability & Failure Mechanisms
+ Packaging for High-Speed Electrical Interconnect
+ RF Components & Modules
+ Additive Manufacturing & 3D Printed Electronics
+ Brain-like Neuromorphic Chip Assembly
+ MEMS/Wearable devices
+ Resilient Packaging for Autonomous System
Low Power, Low Temperature & Ultra Low Noise System Packaging

This conference is a perfect opportunity for you to communicate, interact, exchange technical ideas, and discuss your latest novel research findings in Heterogeneous integration and packaging technologies with experts from industry and academia. In addition to the regular sessions, there is an “Early Career Researchers’ (ECR)” session for young researchers with less than 2-year experience in their professions and all students including Ph.D. to hold fruitful communications with the experts. The ECR sessions have been held as a poster session in the past conferences. Since ICSJ2022 is a hybrid virtual and on-site event, all ECR speakers of accepted abstracts must submit a professionally pre-recorded video of their poster presentation prior to the actual on-site face-to-face poster presentation. Authors are invited to submit an abstract through our website https://www.ieee-csj.org.

The abstract deadline is May 29, 2022. Notification of acceptance will be sent by July 15, 2022, and the authors are requested to submit a 4-page manuscript by September 11, 2022 for the Technical Digest which will be available via IEEE Xplore Digital Library, whereas the authors for the ECR session are required to submit a 2-page manuscript.

Presentation options for the hybrid event:

ICSJ2022 will be a hybrid event for on-site meetings held in Kyoto University Clock Tower Centennial Hall, Kyoto, Japan and virtual meetings via online video conferencing, and the authors are requested to choose from the following options to give their presentation:

1) On-site oral presentation (remote discussion via interactive voice is available)
2) Virtual live and interactive oral presentation (remote discussion via interactive voice is available)
3) Virtual live and one-directional oral presentation (remote discussion via chat is available)
4) On-demand pre-recorded presentation (viewing only)

For plenary, special session, and invited speakers, the authors are requested to choose between option 1 and 2 to give their presentation. Whereas contributed speakers are requested to prioritize the options when submitting their proceeding paper and the mode of presentation will be assigned according to the capacity of the conference hall and speakers’ preference.

Plenary, Special Session and Invited Speakers:

As of March 2022, the confirmed speakers are listed below:

Plenary Speakers:

Special Session Speakers:

Invited Speakers:

Chang Hyeon Ji (Ewha Womans University)

The above list of speakers will be updated and announced on the ICSJ official website.
ICSJ2022 Steering Committee:

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On-site Conference Venue:
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Yoshidahonmachi, Sakyo-ku, Kyoto, 606-8501